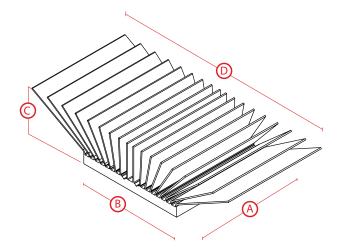


Ultra High Performance BGA Cooling Solutions w/ Thermal Tape Attachment

ATS PART # ATS-52250G-C2-R0

Features & Benefits

- » maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- Fabricated from extruded aluminum, which minimizes thermal resistance from the base to the fins, reduces weight and keeps costs low
- » Higher performance helps ensure reliable product life at a lower cost than other extruded heat sinks





Thermal Performance

*Image above is for illustration purposes only.

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1.0	5.2	4	
300	1.5	4.1		
400	2.0	3.6		
500	2.5	3.2		
600	3.0	2.9		
700	3.5	2.7		
800	4.0	2.6		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
25 mm	25 mm	12.5 mm	44.9 mm	SAINT-GOBAIN C675	BLUE-ANODIZED

NOTES:

- Dimension C = heat sink height from bottom of the base to the top of the fin field.
- Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).

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